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Part Number: APTD1608SECK/J3-PF Hyper Red

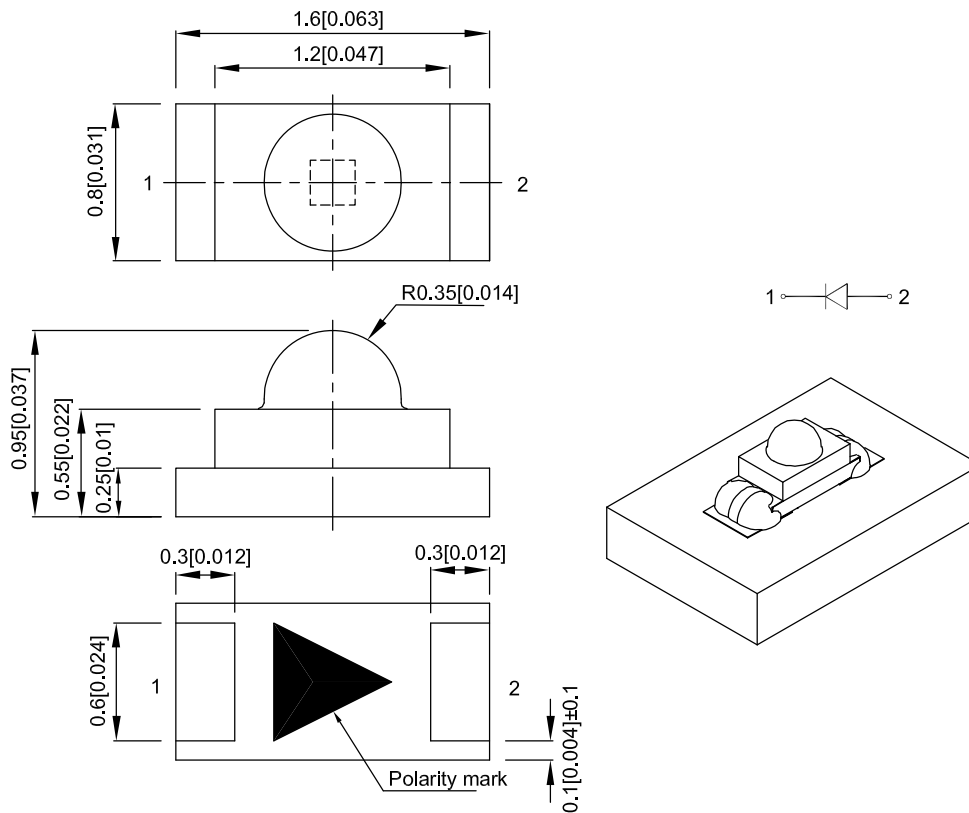
Features

- 1.6mmX0.8mm SMD LED, 0.95mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel .
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red device is based on light emitting diode chip made from AlGaInP.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.15(0.006")$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Emitting Color (Material)	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APTD1608SECK/J3-PF	Hyper Red (AlGaInP)	Water Clear	1900	2700	60°
			*500	*800	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous Flux: +/-15%.
- * Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Hyper Red	640		nm	I _F =20mA
λ _D [1]	Dominant Wavelength	Hyper Red	625		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Hyper Red	20		nm	I _F =20mA
C	Capacitance	Hyper Red	27		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Hyper Red	2.2	2.8	V	I _F =20mA
I _R	Reverse Current	Hyper Red		10	uA	V _R =5V

Notes:

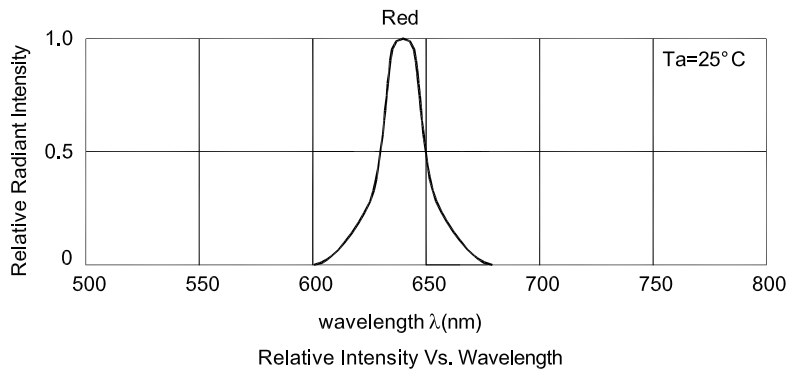
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Values	Units
Power dissipation	84	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

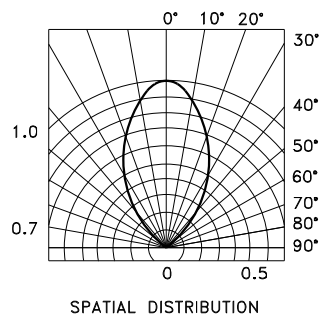
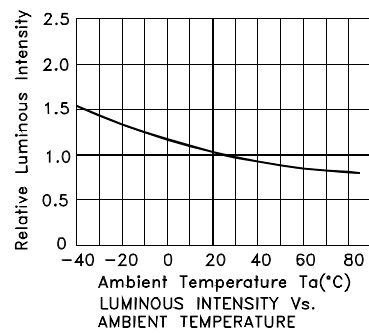
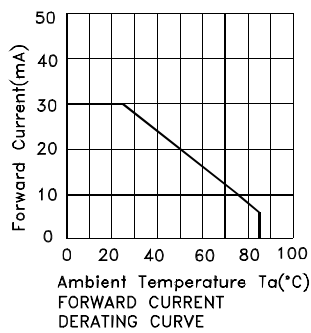
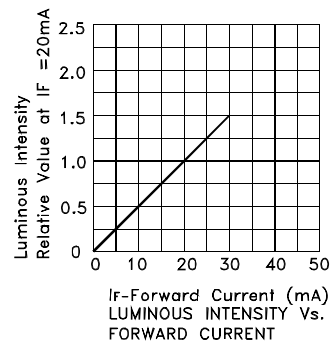
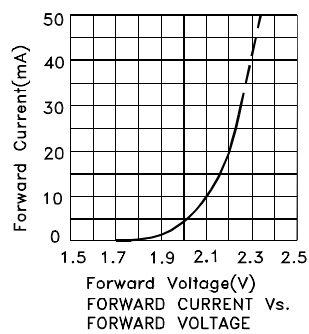
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



Hyper Red

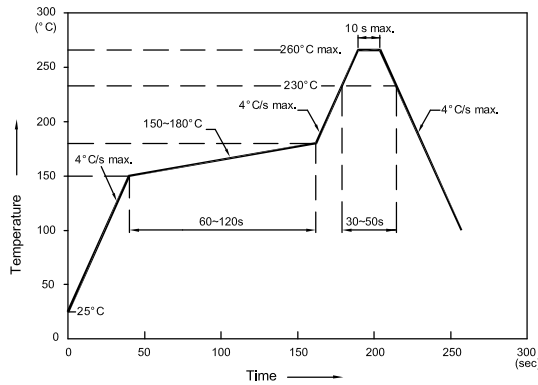
APTD1608SECK/J3-PF



APTD1608SECK/J3-PF

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

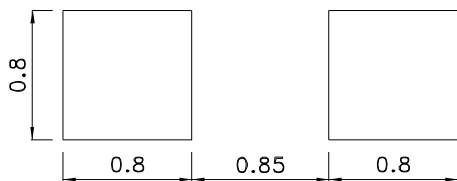
Reflow Soldering Profile For Lead-free SMT Process.



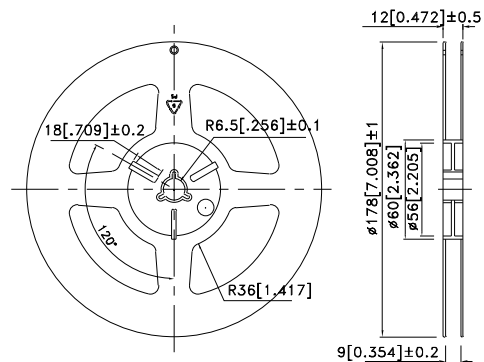
NOTES:

1. We recommend the reflow temperature 245°C (+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

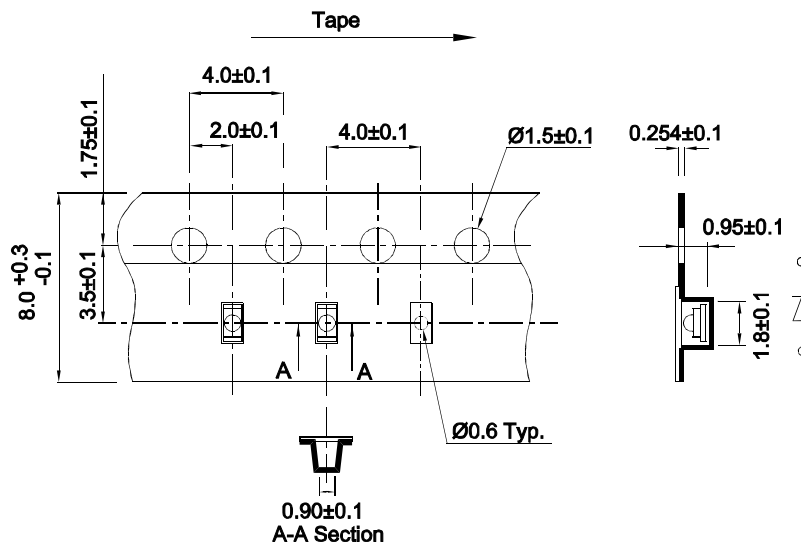
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

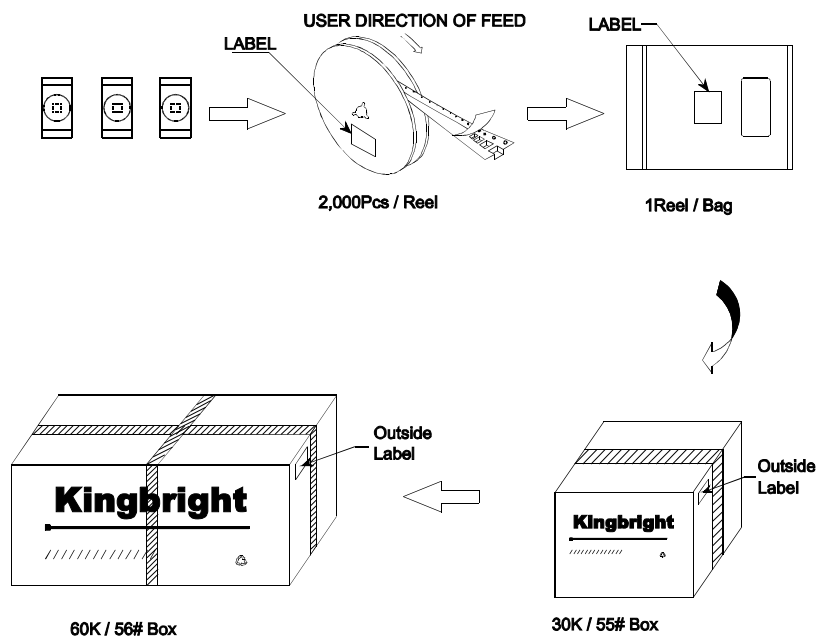



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

APTD1608SECK/J3-PF



<h1>Kingbright</h1>	
P/NO: APTD1608xxx	
QTY: 2,000 pcs	Q.C. Q C XXXX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 <small>XX</small>	
RoHS Compliant	

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